

Alimentação remota de circuitos implantados por meio de acoplamento indutivo

Fernando Rangel de Sousa



Quem somos

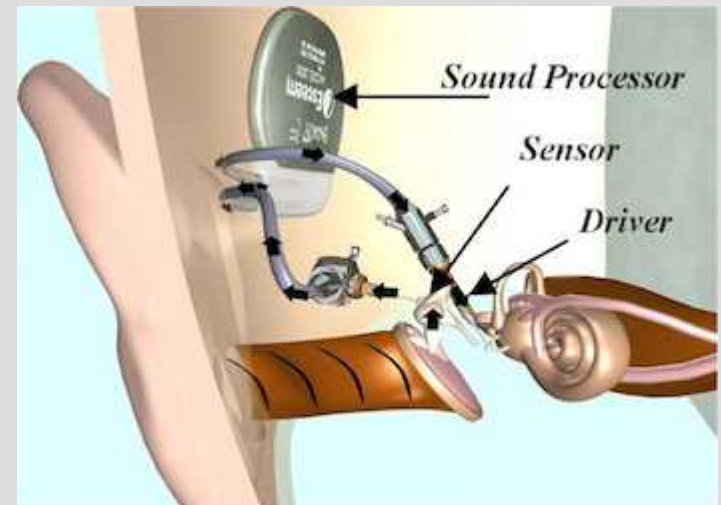
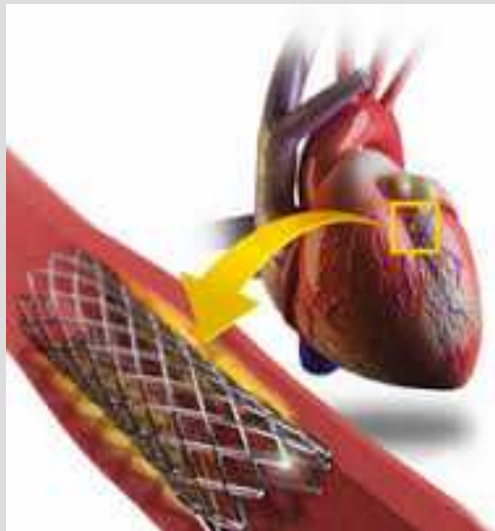


O que fazemos

- Pesquisa em Radiofrequência
- Temas multidisciplinares / transversais
 - Petróleo/gás
 - Zootecnia
 - Biomédica
 - Instrumentação e medição
 - ...
- Ferramentas (meio)
 - Microeletrônica (projetamos chips)
 - Instrumentação (com e sem fio)
 - SDI (Instrumentação + SDR)
 - Simulação eletromagnética
- Medimos o que fazemos

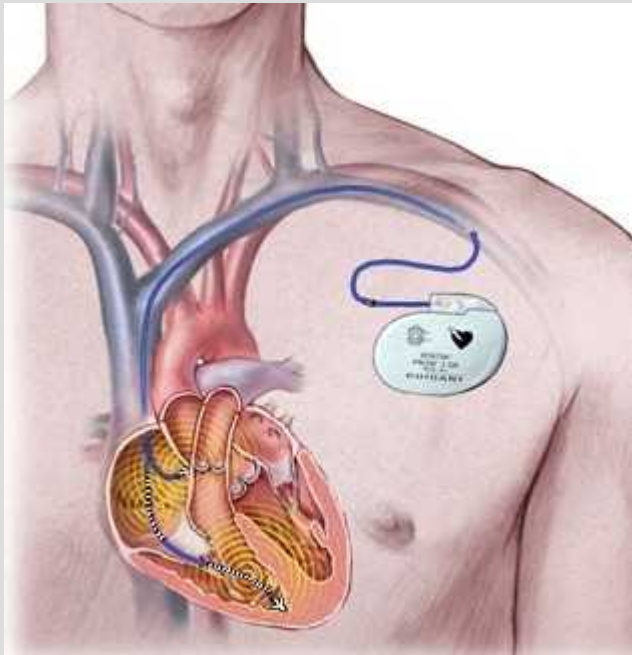
Implantes médicos

- Um implante pode ser um dispositivo médico desenvolvido para substituir ou dar suporte a uma estrutura biológica danificada, monitorar sinais fisiológicos, prover estímulos, administrar medicamentos localmente, recuperar funções sensoriais, etc.



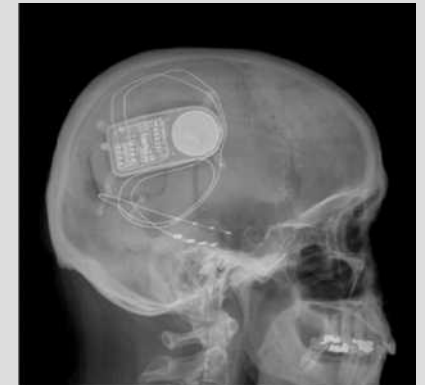
Implantes eletrônicos

▣ Marcapassos

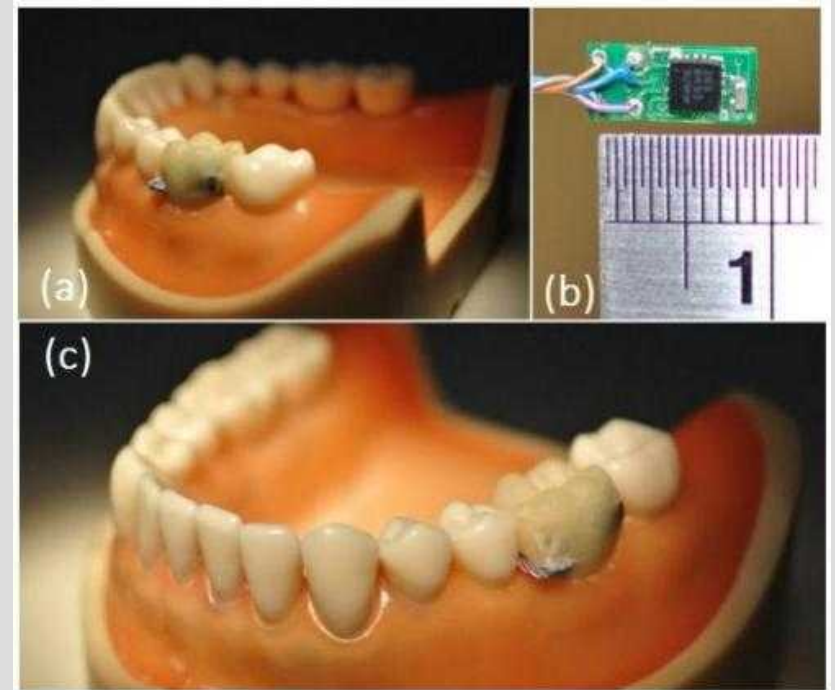
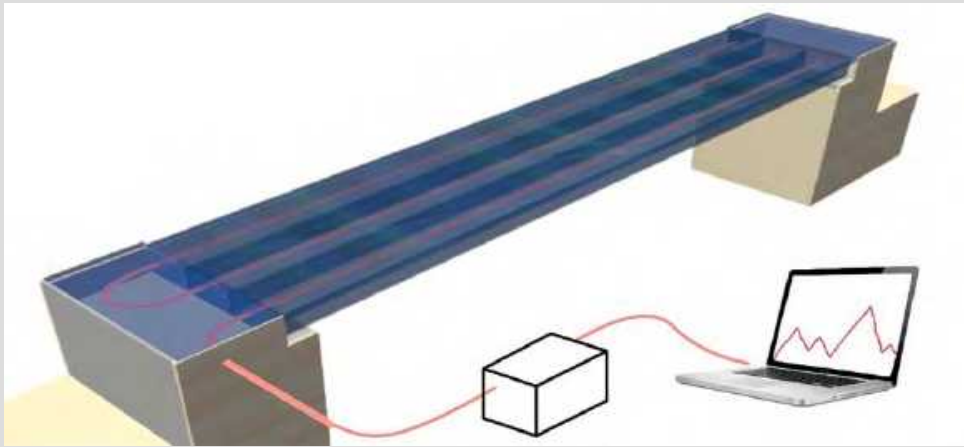


Implantes eletrônicos

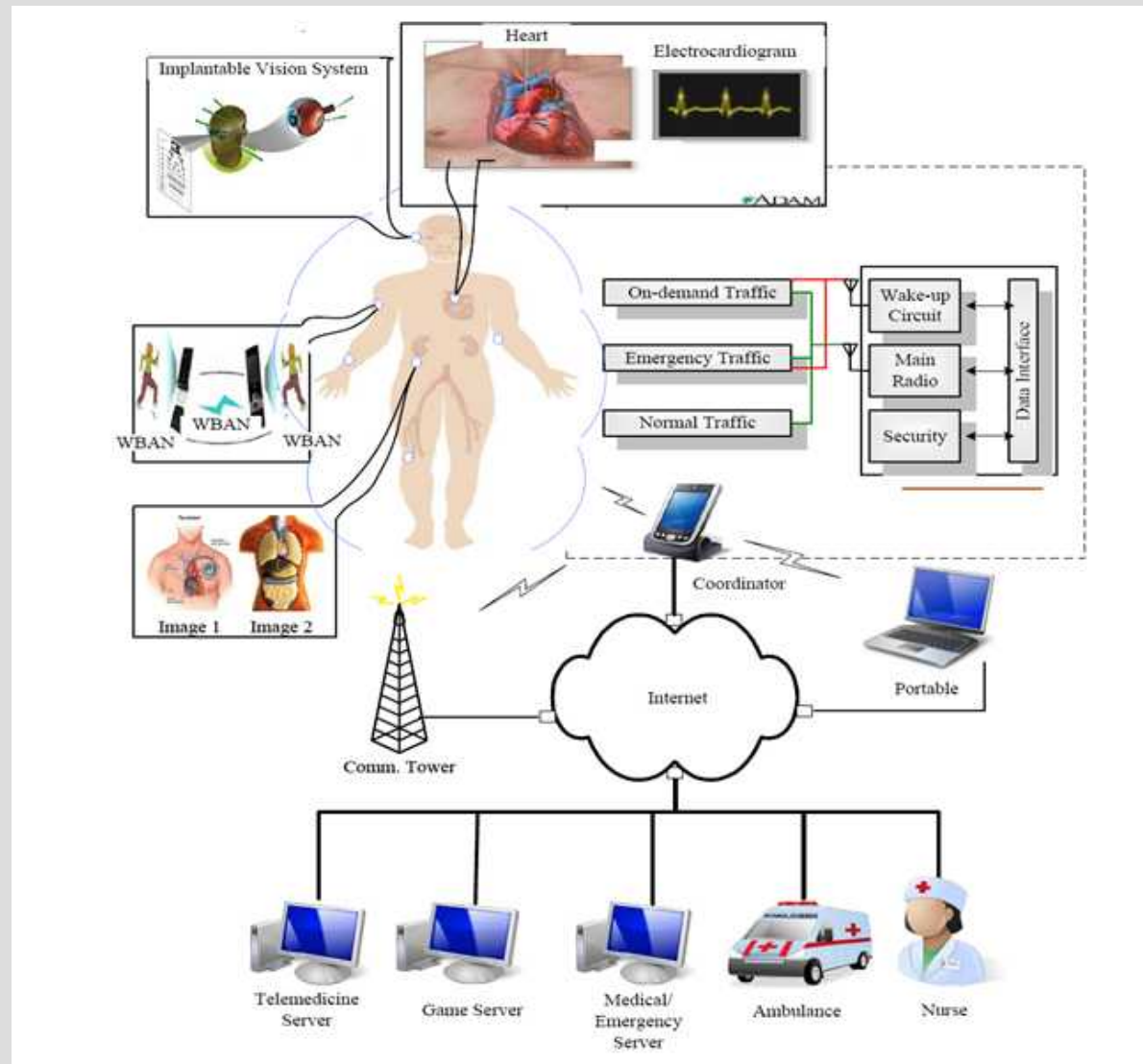
Neuroestimuladores



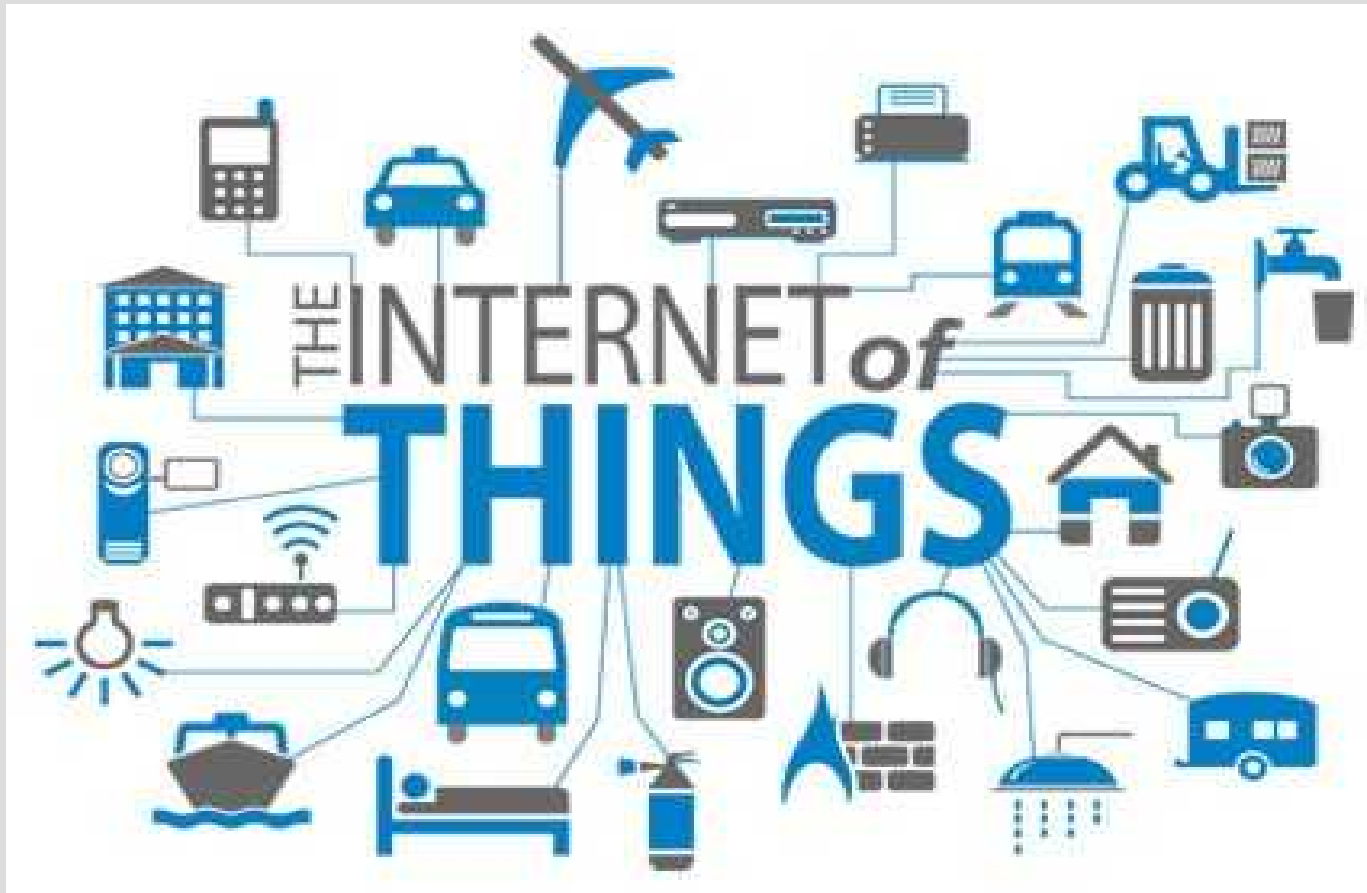
Outros implantes



Redes corporais (WBAN)



Internet das Coisas (IoT)

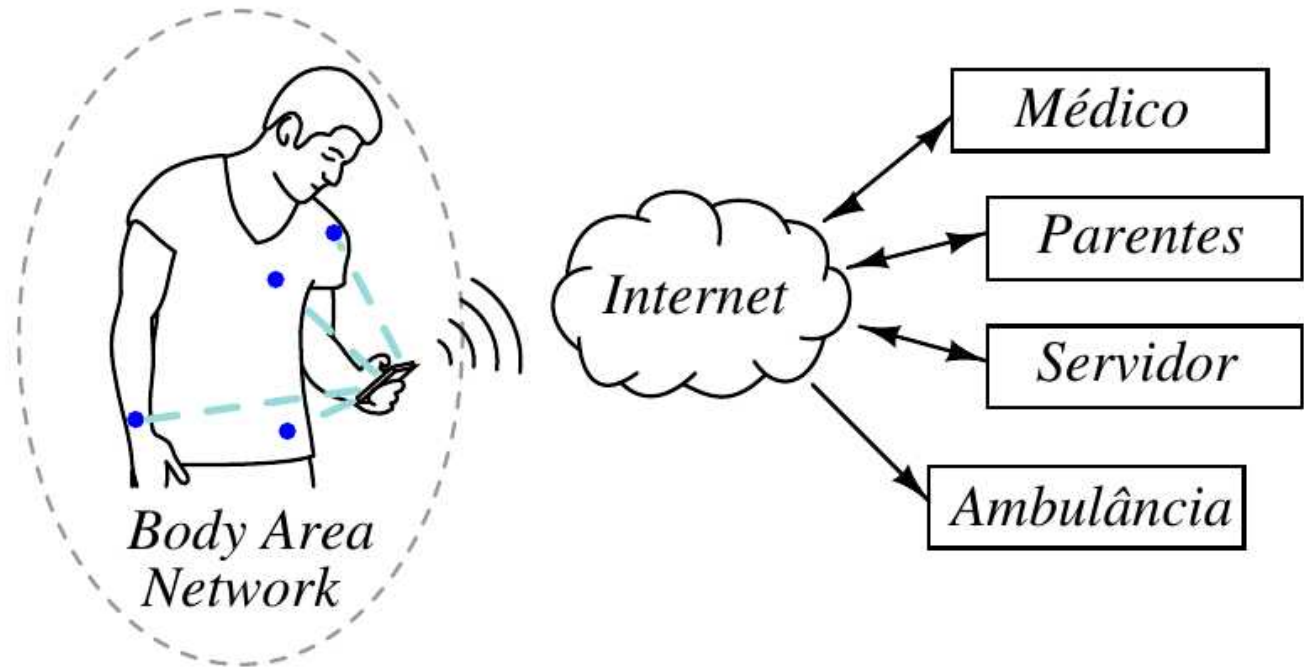


Trilhões de dispositivos conectados

IoT

- *Sensores vestidos ou implantados:*

- *Temperatura*
- *Ritmo cardíaco*
- *Pressão arterial*
- *Glicose*
- *Movimento*
- *Respiração*



Eletrônica Invisível (IoT)

Achieving Optimal Efficiency in Energy Transfer to a CMOS Fully-Integrated Wireless Power Receiver

Fabian L. Cabrera and F. Rangel de Sousa, *Senior Member, IEEE*

IN the near future billions of devices will be interconnected, enabled by the Internet of Things (IoT) [1]. Several applications are envisaged in different domains including transportation, agriculture, smart homes and healthcare [2]. The transition from idea to reality depends on addressing problems which remain unsolved. As stated in the visionary paper by Mark Weiser [3], *“the most profound technologies are those that disappear”*, however, the physical size as well as the cables used to deliver energy to current IoT-enabled devices are not compatible with the ongoing paradigm shift.



Mark Weiser

Realidade: Eletrônica Visível !

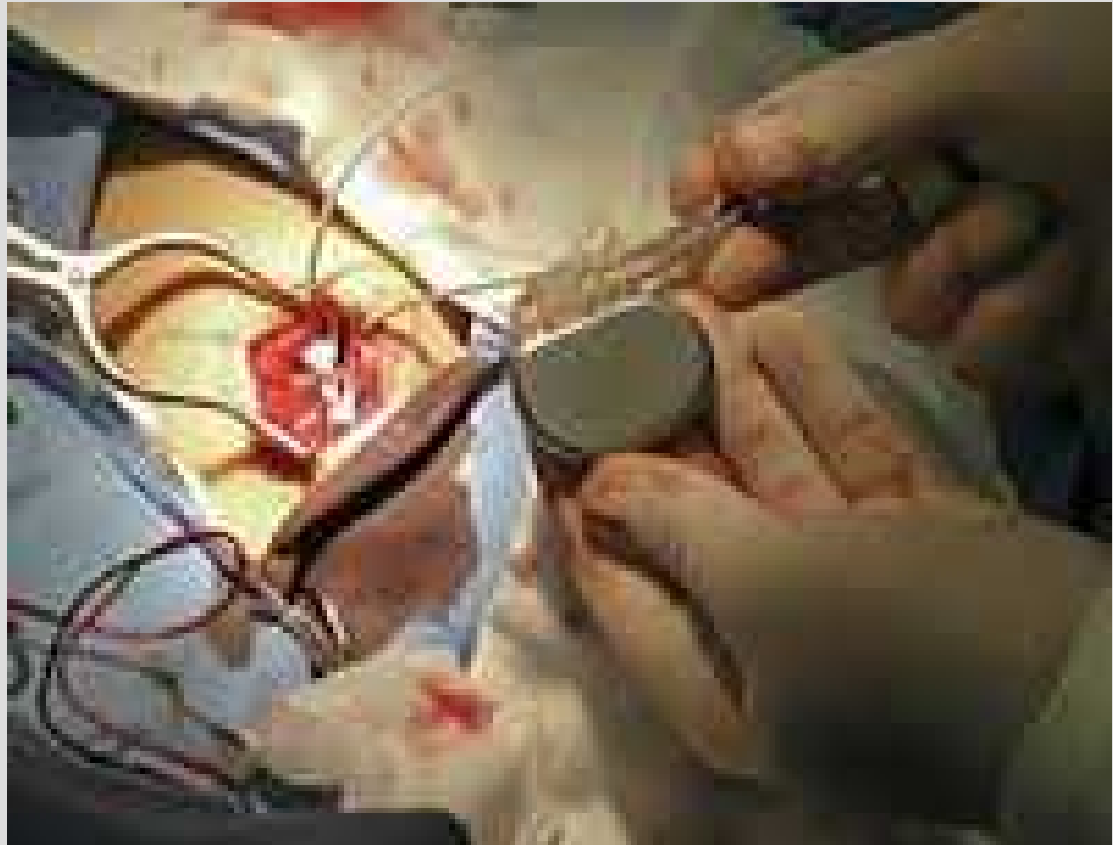


Alimentação de implantes

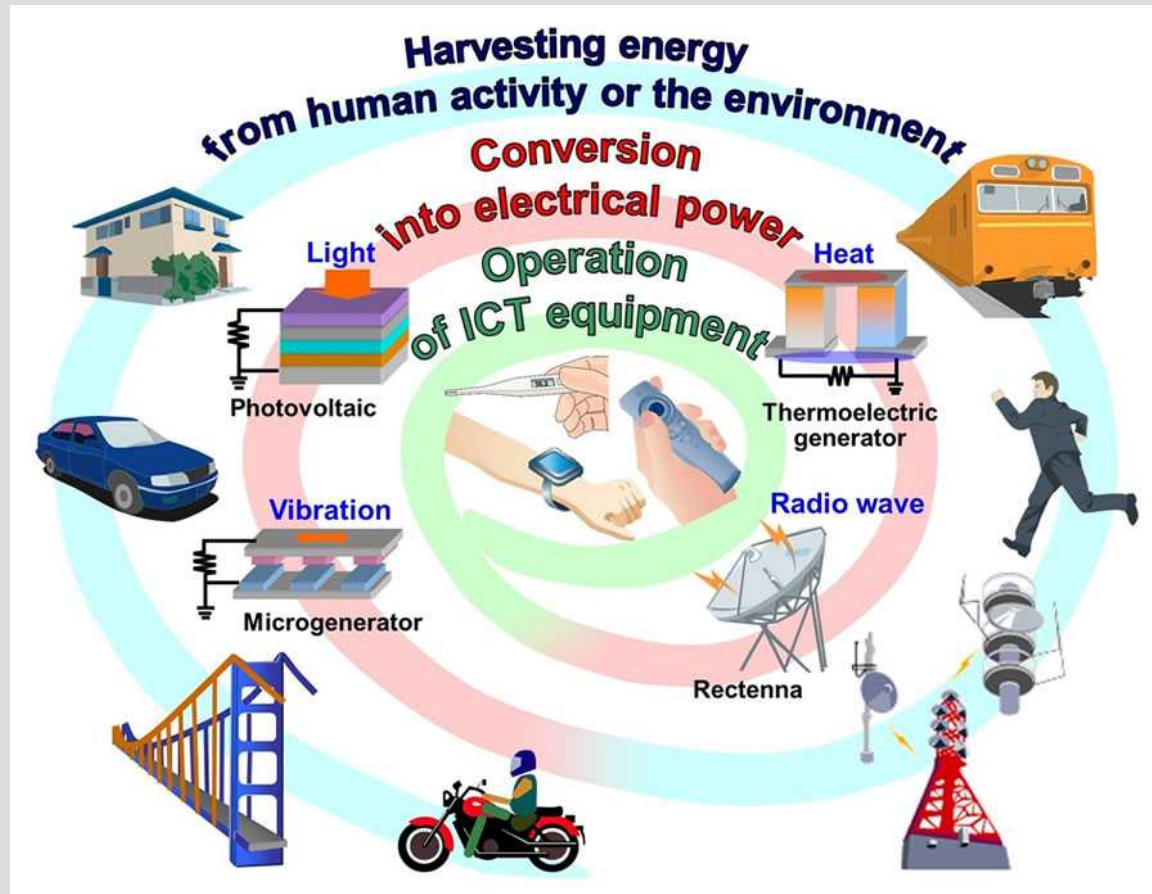
Baterias



Troca de baterias!



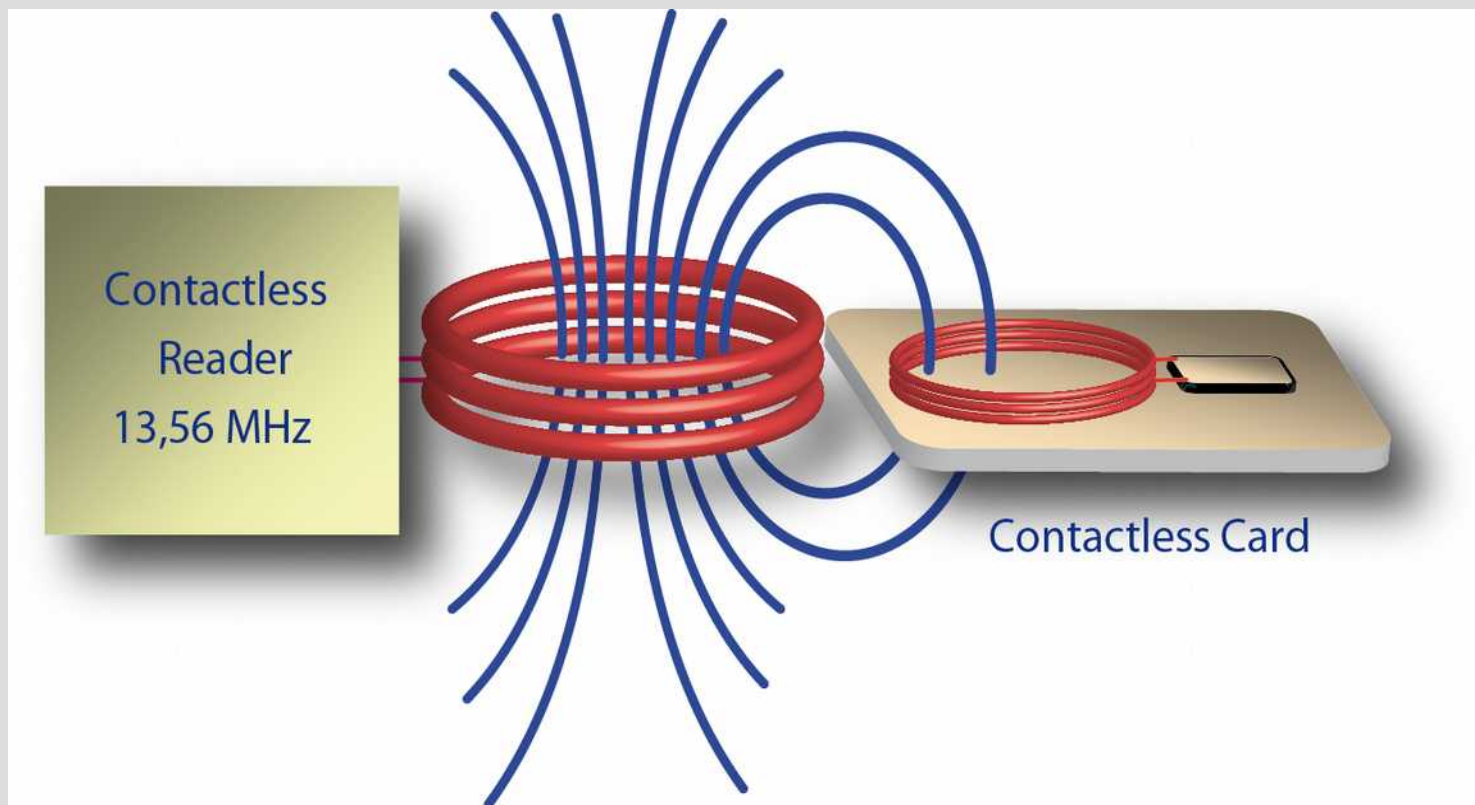
Alternativas: Energy Harvesting



Há diversas formas de energia disponíveis .
O desafio é captá-las com eficiência

Acoplamento indutivo

Implementado com sucesso em
RFID, smartcards, etc.

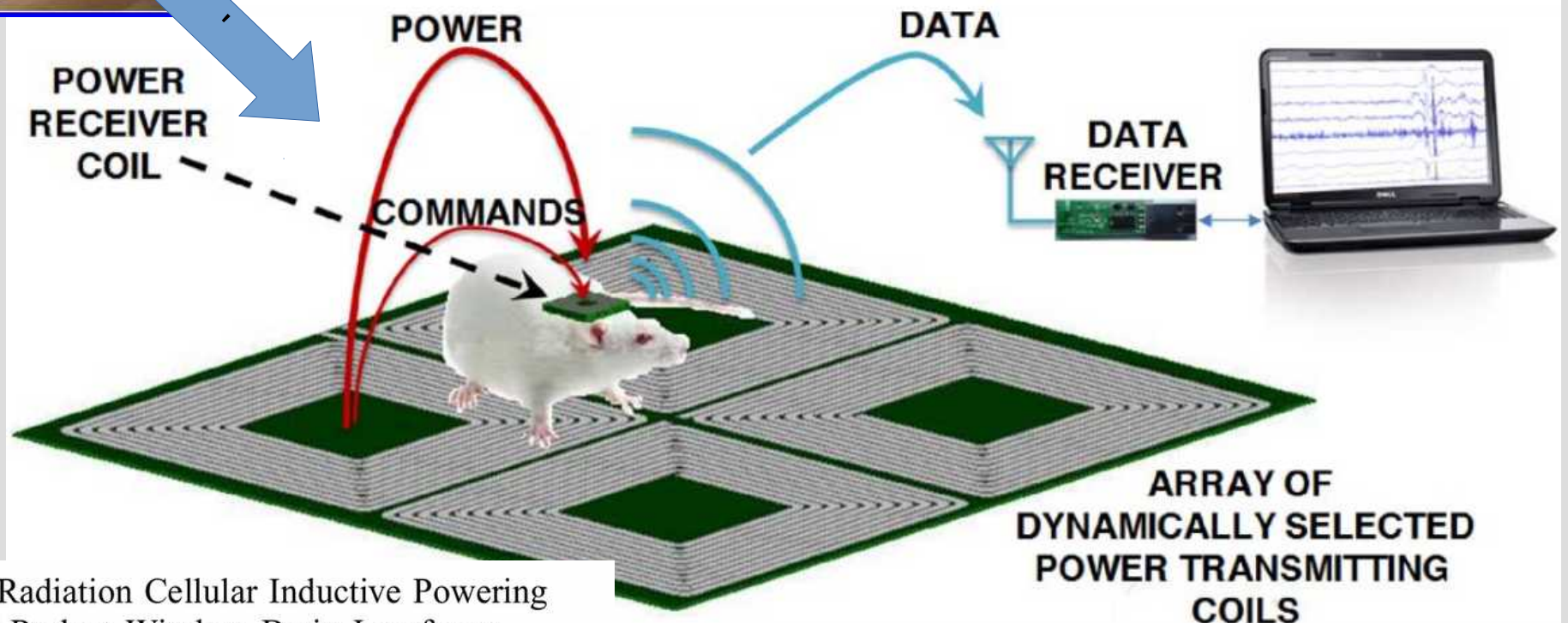


Baseia-se no uso de um transformador com núcleo de ar

Acoplamentos indutivos em aplicações biomédicas

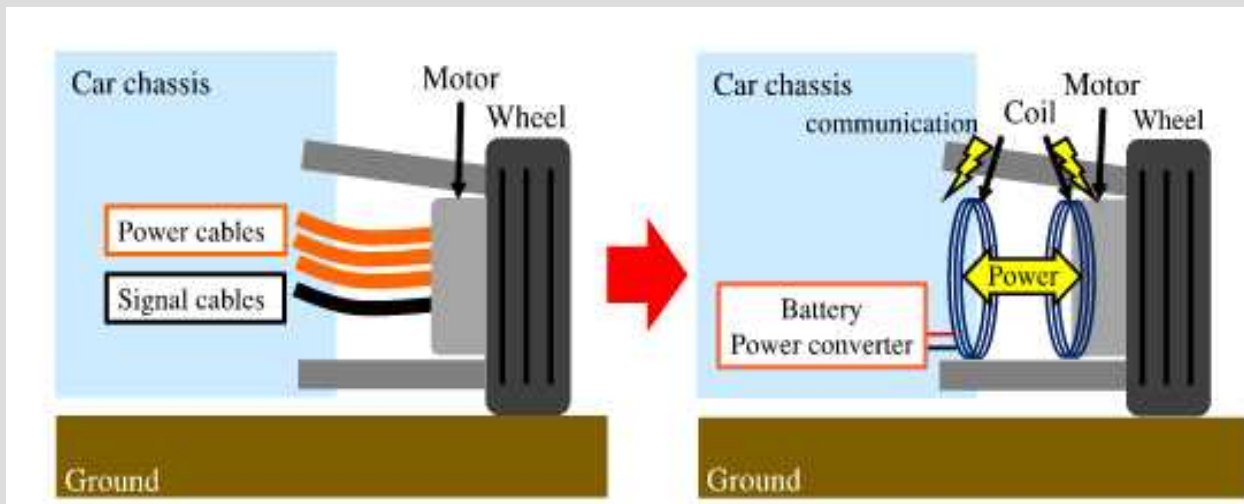


Ao retirar os cabos, permite reduzir interferência em experimentos



Low-Radiation Cellular Inductive Powering of Rodent Wireless Brain Interfaces: Methodology and Design Guide

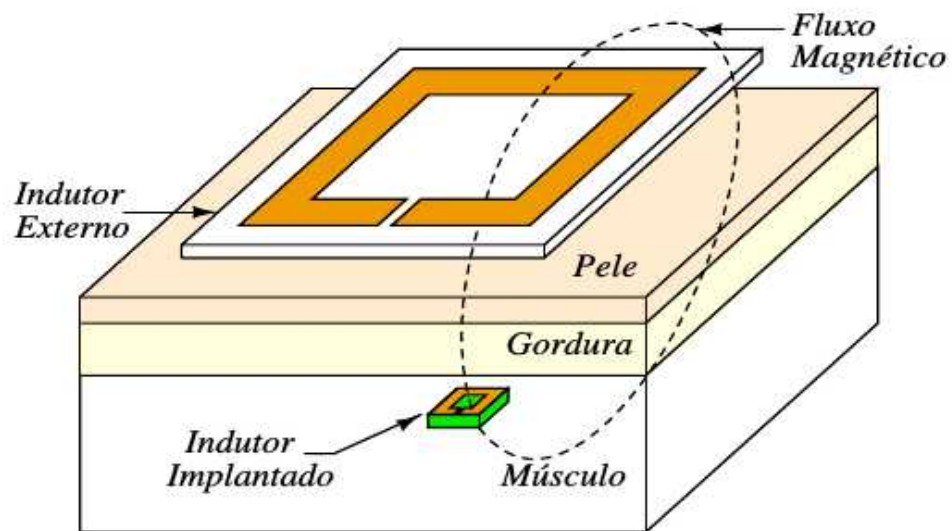
Acoplamentos indutivos em carros elétricos



Development of Wireless In-Wheel Motor Using Magnetic Resonance Coupling

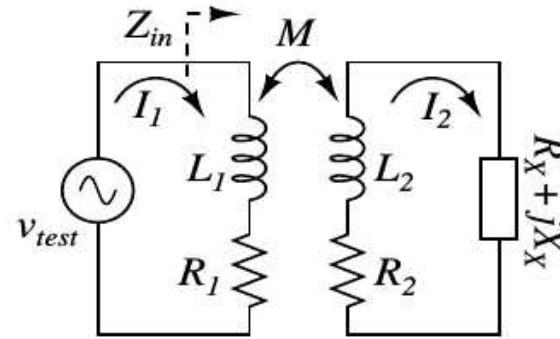
Motoki Sato, *Member, IEEE*, Gaku Yamamoto, Daisuke Gunji, *Member, IEEE*, Takehiro Imura, *Member, IEEE*, and Hiroshi Fujimoto, *Senior Member, IEEE*

Formulação do problema do acoplamento indutivo para implantes



- ▶ Máxima potência é limitada pelo aquecimento dos tecidos.
- ▶ Eficiência deve ser otimizada.
- ▶ O indutor secundário deve ser miniaturizado.
- ▶ Restrição na área do primário é mais flexível.

Eficiência na transferência de Energia



$$M = k\sqrt{L_1 L_2}$$

$$Q_1 = \omega L_1 / R_1$$

$$Q_2 = \omega L_2 / R_2$$

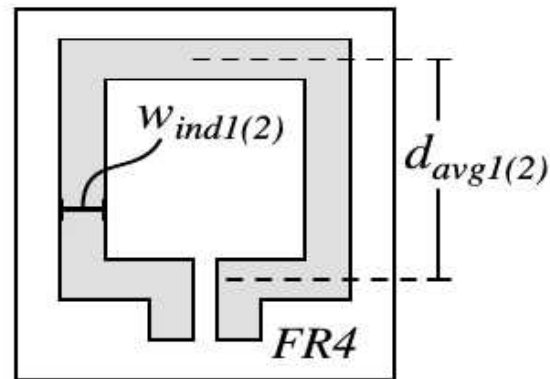
$$p = R_2 / R_X$$

Eficiência

$$\frac{1}{\eta} = \frac{1}{k^2} \cdot \frac{1}{Q_1} \cdot \frac{1}{Q_2} \cdot \underbrace{\left(p + 2 + \frac{1}{p} \right) + p + 1}$$

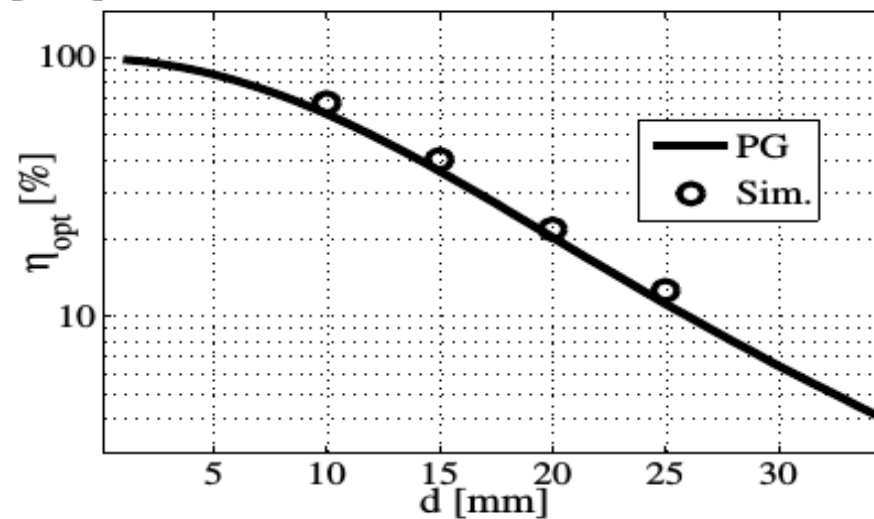
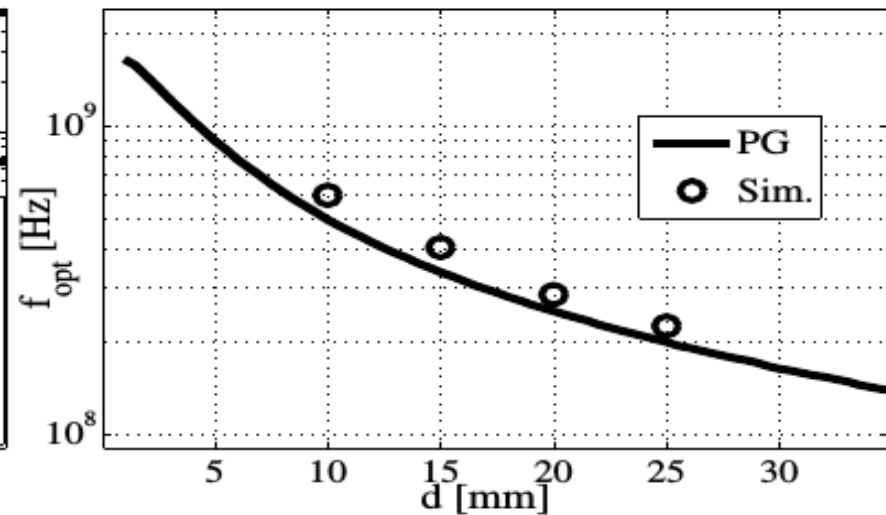
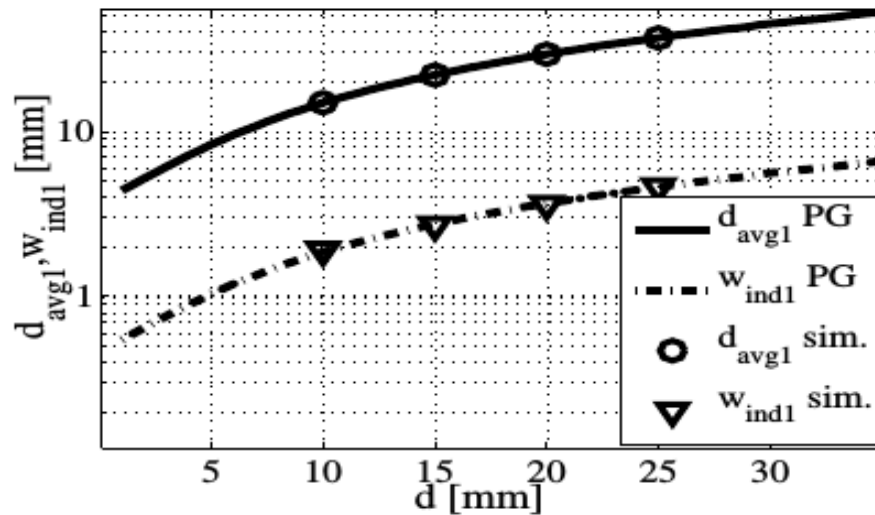
- ▶ Fator de acoplamento
- ▶ Fator de qualidade 1
- ▶ Fator de qualidade 2
- ▶ Dependência com a carga

Otimização do indutor



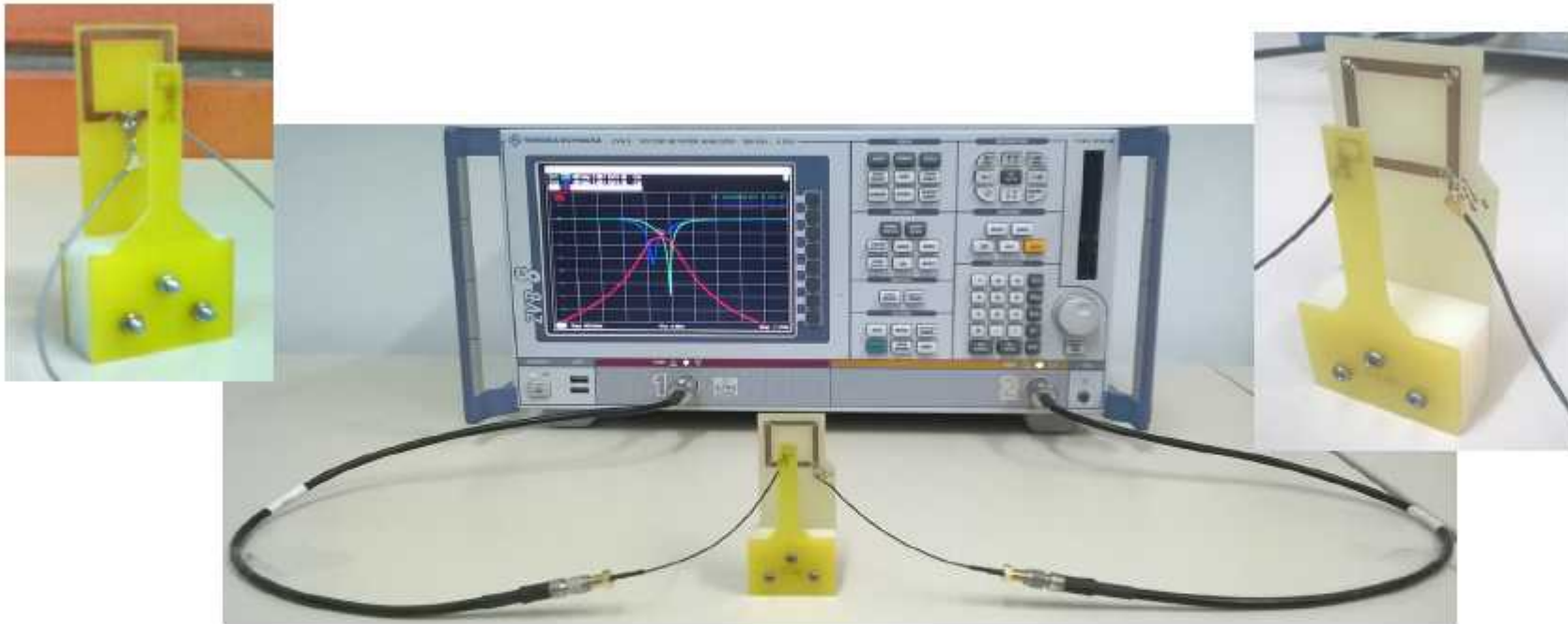
Dados:	O tamanho do indutor implantado	d_{avg2}, W_{ind2}
	A distância entre os indutores	d
Encontrar:	O tamanho do indutor externo	d_{avg1}, W_{ind1}
	A proporção da carga	p
	A frequência	f
Para:	maximizar a eficiência	η

Resultados da otimização



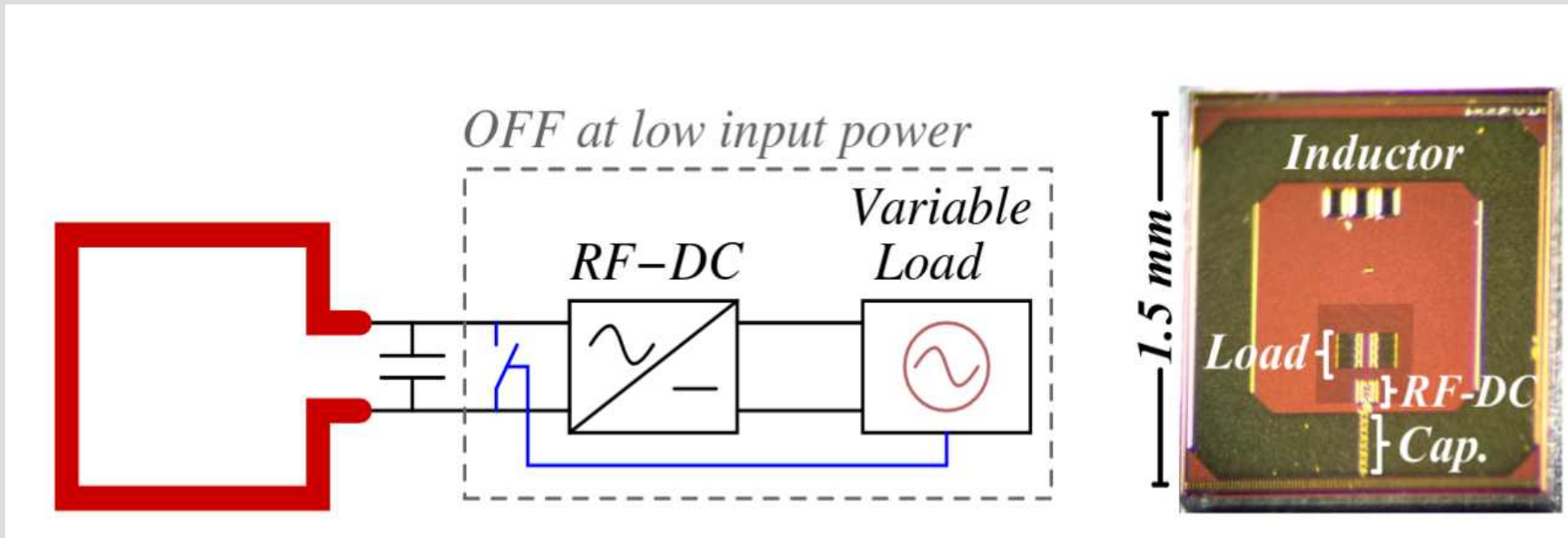
Indutor interno de 4 mm.

Verificação experimental

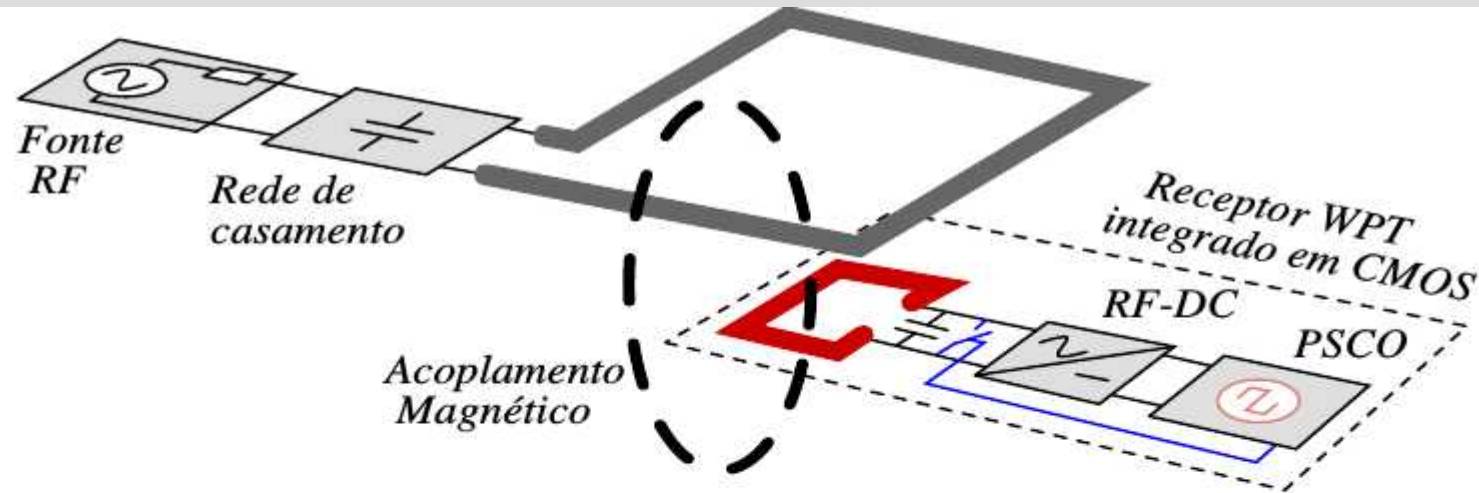


d_{avg2} [mm]	d_{avg1} [mm]	d [mm]	N	C_D [pF]	η_{max} [%]	$f_{\eta_{max}}$ [MHz]
4	22	15	1	–	30	415
4	22	15	4	1.5	30	980

Indutor Integrado em Silício



Sistema de transferência de energia para implantes



$$\eta_T = \frac{\eta_{com}\eta_{RT}}{\frac{1}{k^2 Q_{1r} Q_{2r}} \left(p + 2 + \frac{1}{p} \right) + p + 1} \quad (3)$$

Parte	Receptor				Transmissor	
	η_{com}	Q_{2r}	η_{RT}	p	k	Q_{1r}
Objetivos						
Variáveis de projeto	<ul style="list-style-type: none"> • Valor fixo: $D=0,5$ 	<ul style="list-style-type: none"> • Indutor integrado • Frequência (f) 	<ul style="list-style-type: none"> • Retificador • Carga (R_V) • Potência (P_V) 			<ul style="list-style-type: none"> • Indutor Primário

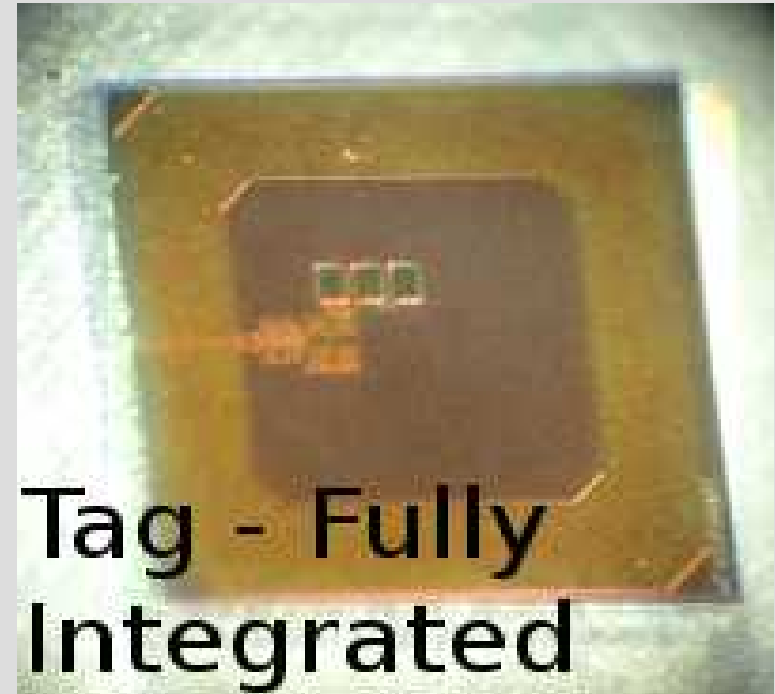
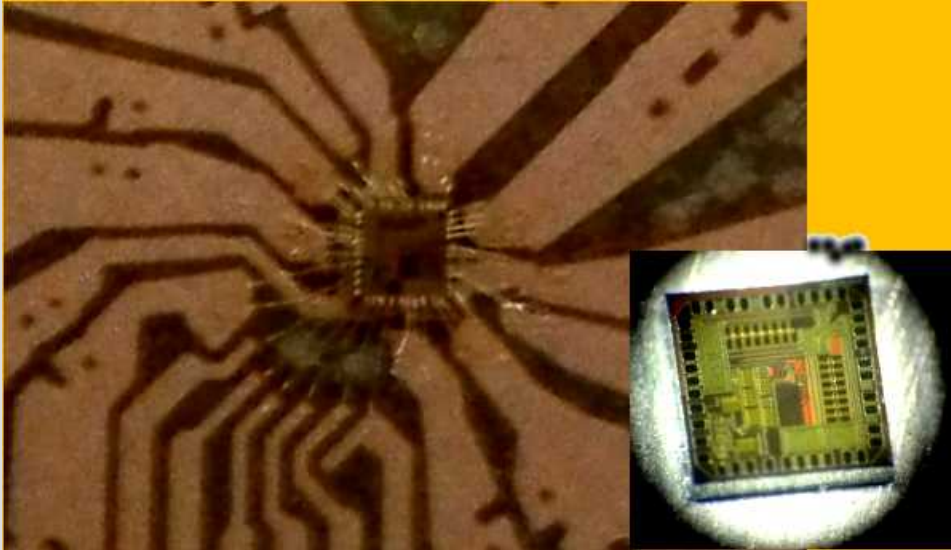
Caracterização do sistema



d [mm]	η_{max} [%]
5	7.71
10	1,02
15	0,29
20	0,07

Chips projetados para o sistema

Class-E Power Amplifier



Tag - Fully Integrated

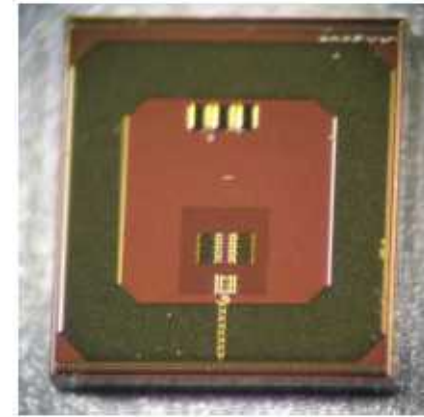
Future



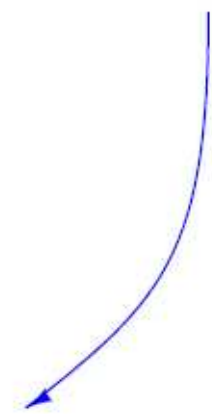
12 cm^3



$0,75 \text{ cm}^3$



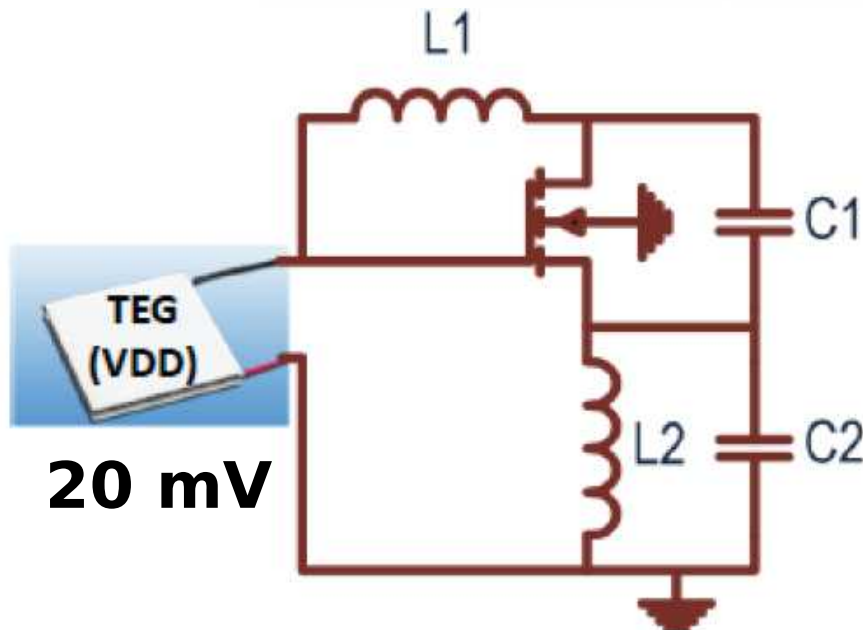
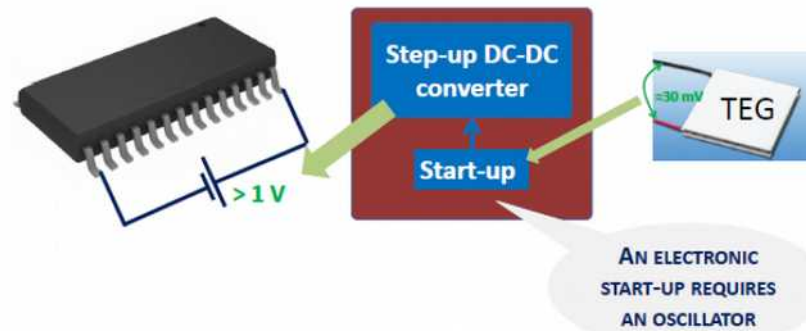
$0,0007 \text{ cm}^3$



Outline

- **WBAN Review**
- **WBAN Research at UFSC**
 - **HBC Channel characterization**
 - **RF-powered temperature sensor**
 - **Wireless power transmission to miniaturized implants**
 - **Energy harvesting**
 - **ISFET for pH and glucose measurement**
- **Concluding remarks**

Thermoelectric energy harvesting



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ISFET sensor

• Partnership with CCS/UNICAMP

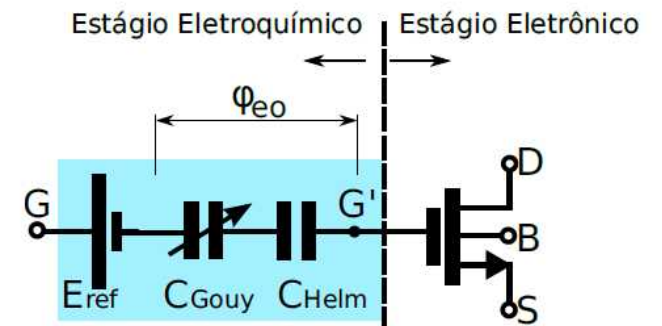
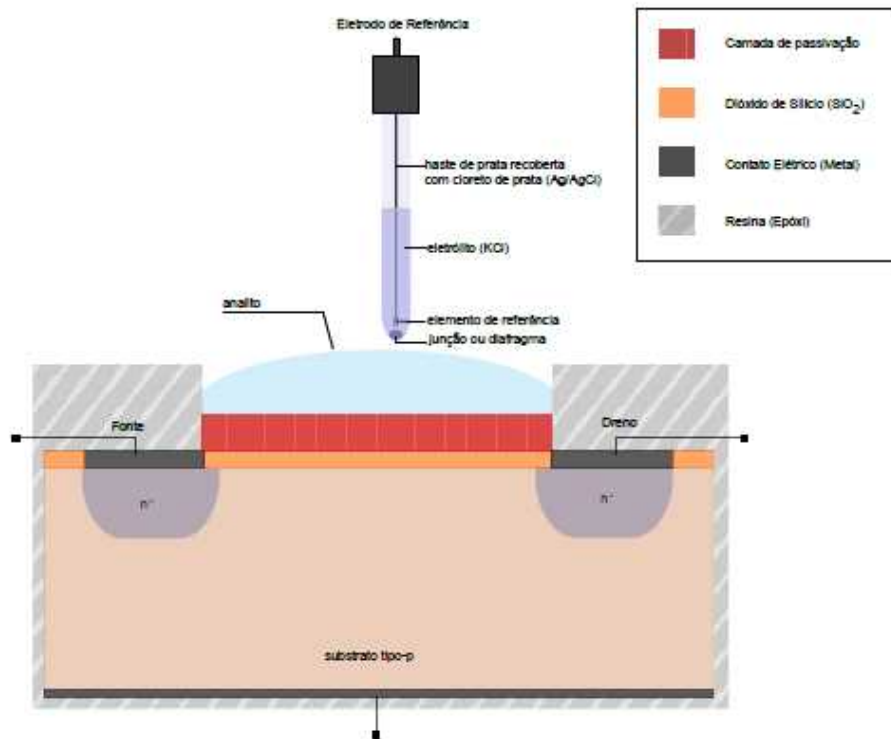
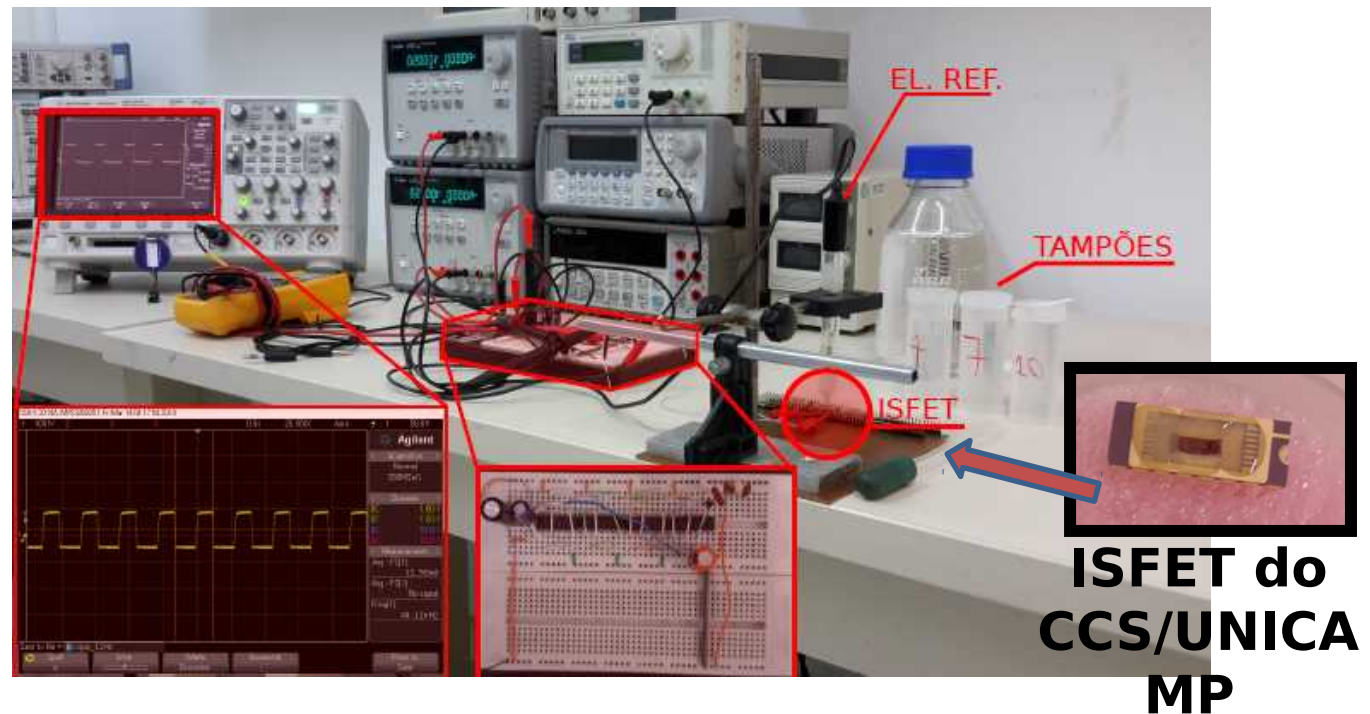
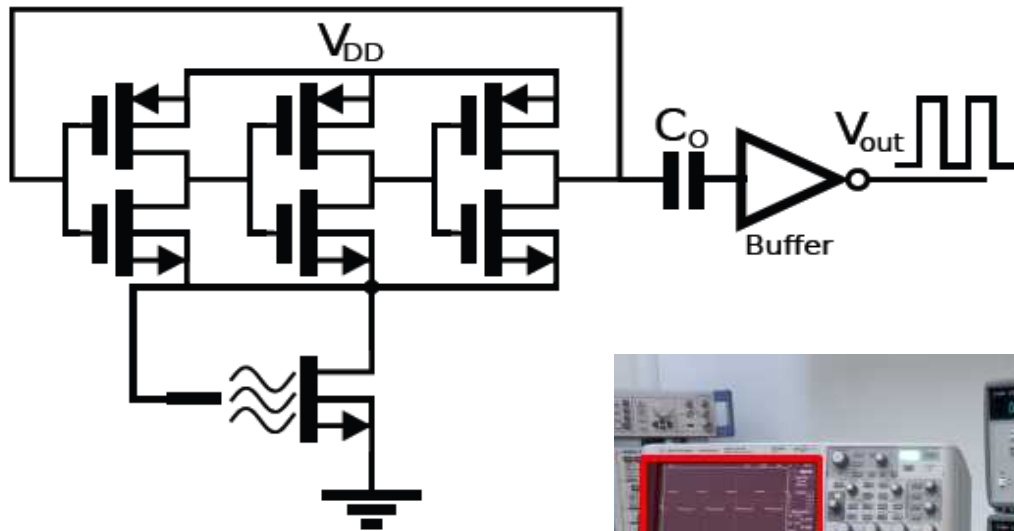


Figura 3: Macro-modelo do ISFET

PH controlled oscillator – PHCO



Sensor de permissividade por microondas

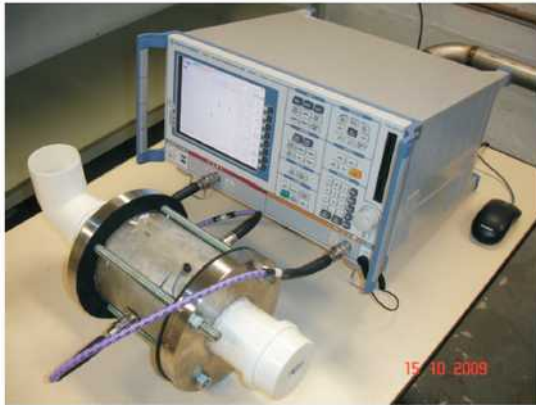
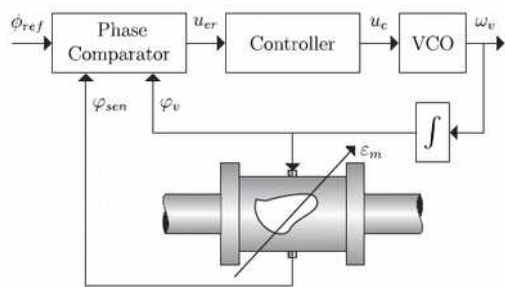


Figura 6.1: Protótipo desenvolvido para experimentos, conectado ao analisador de rede.



(b)

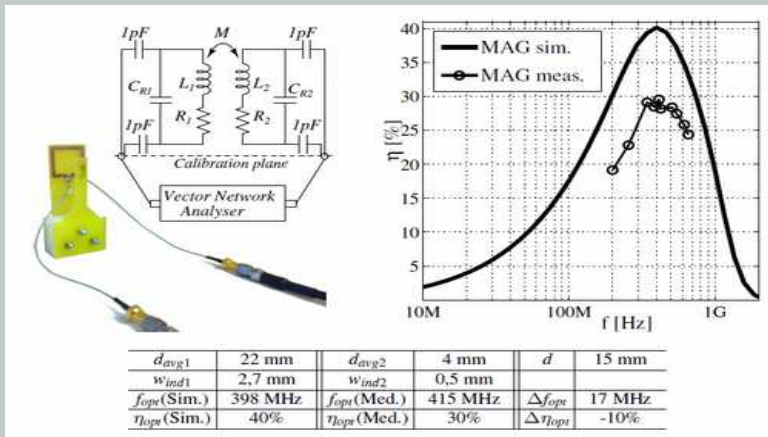
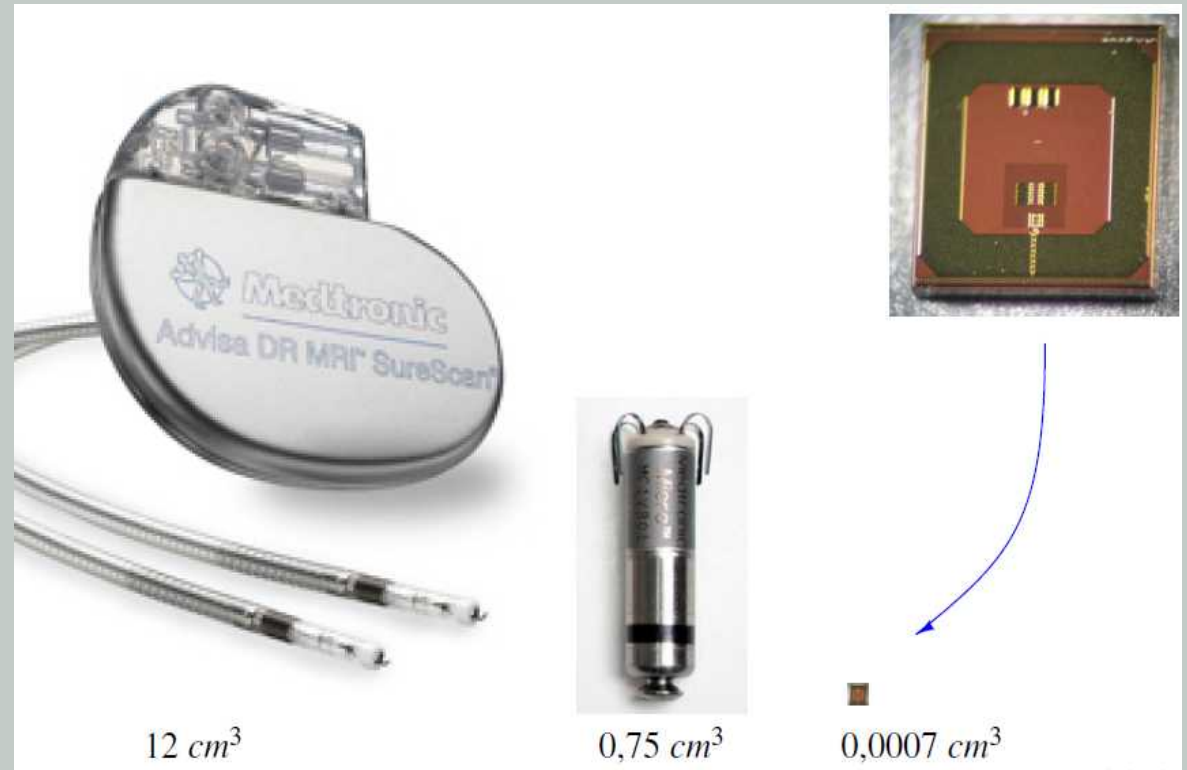
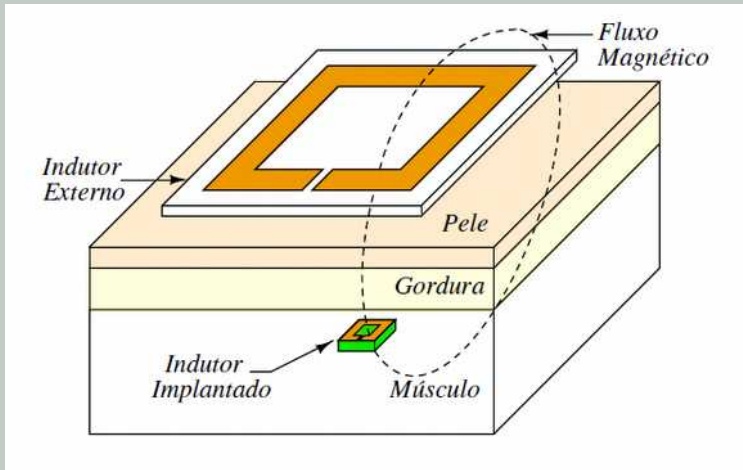
(c)



Sensor measured

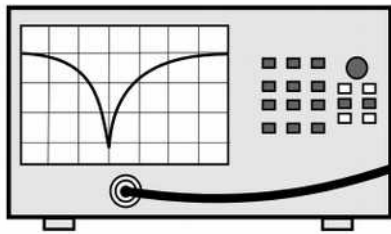


Chip para alimentar implantes miniaturizados

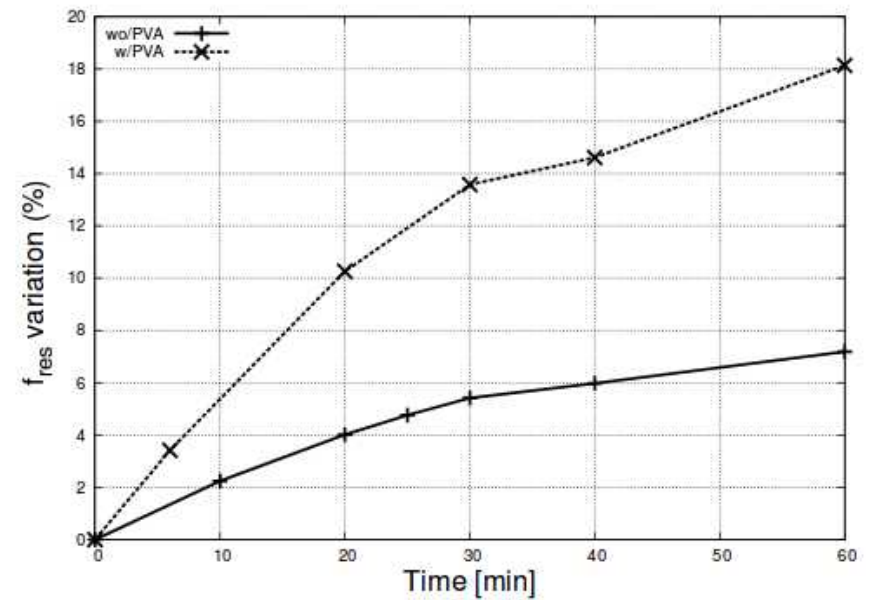
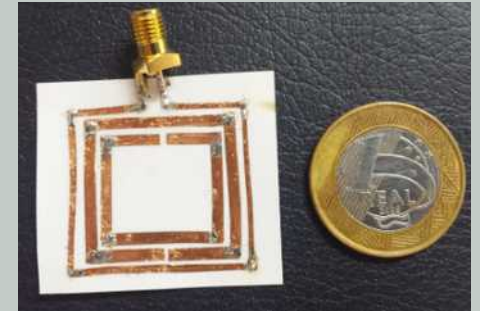
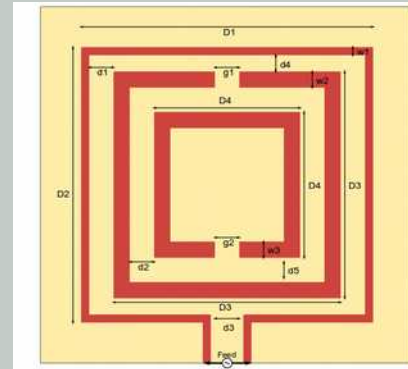
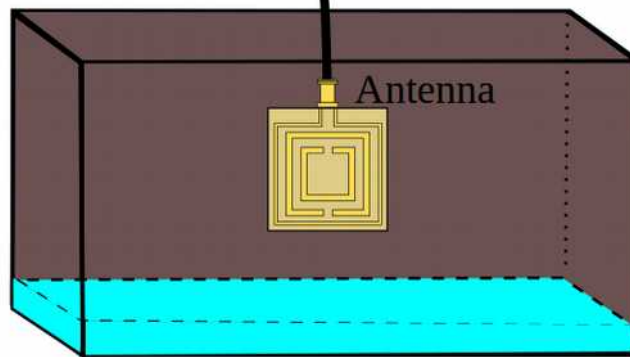


Sensores em substratos orgânicos

VNA

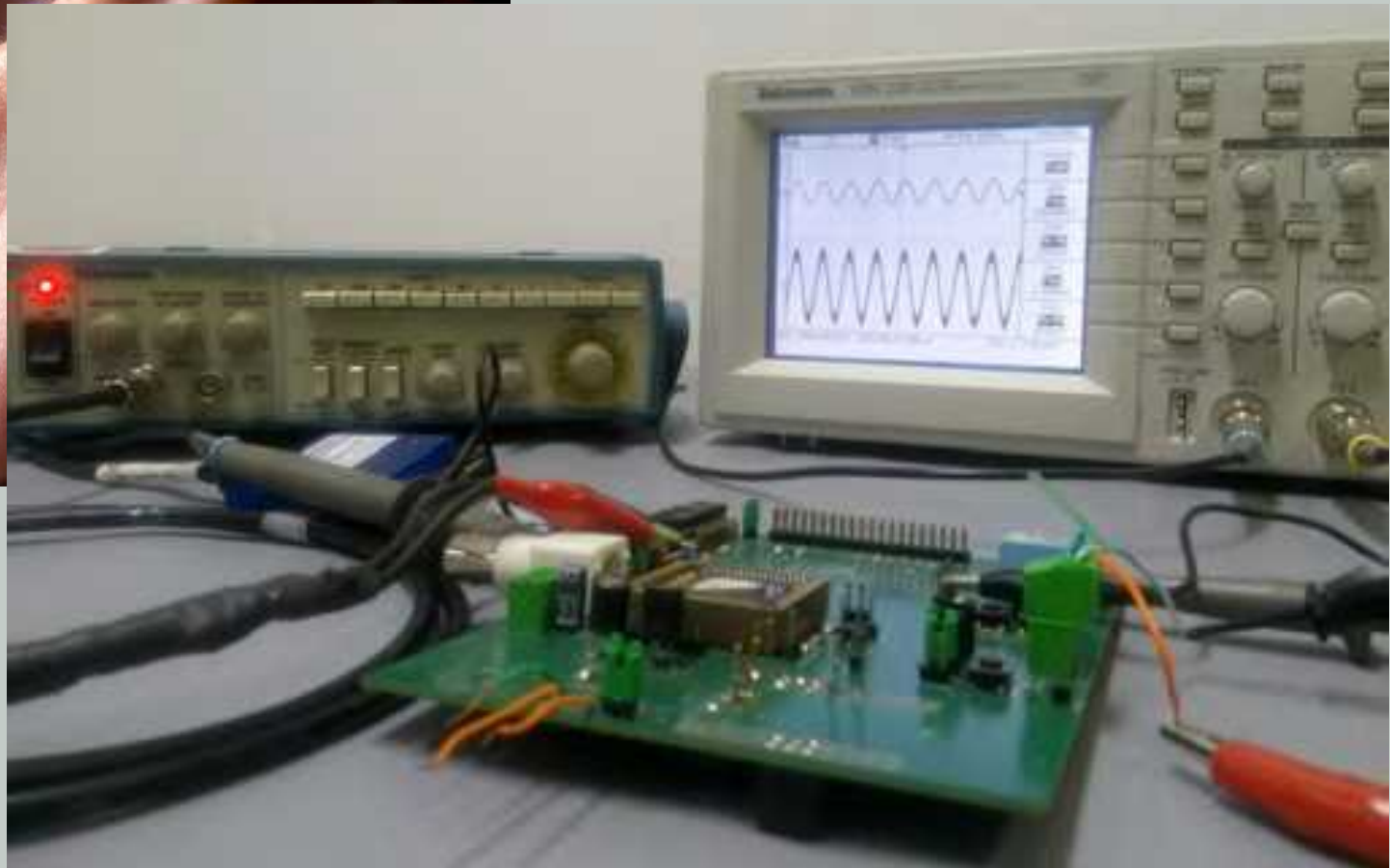
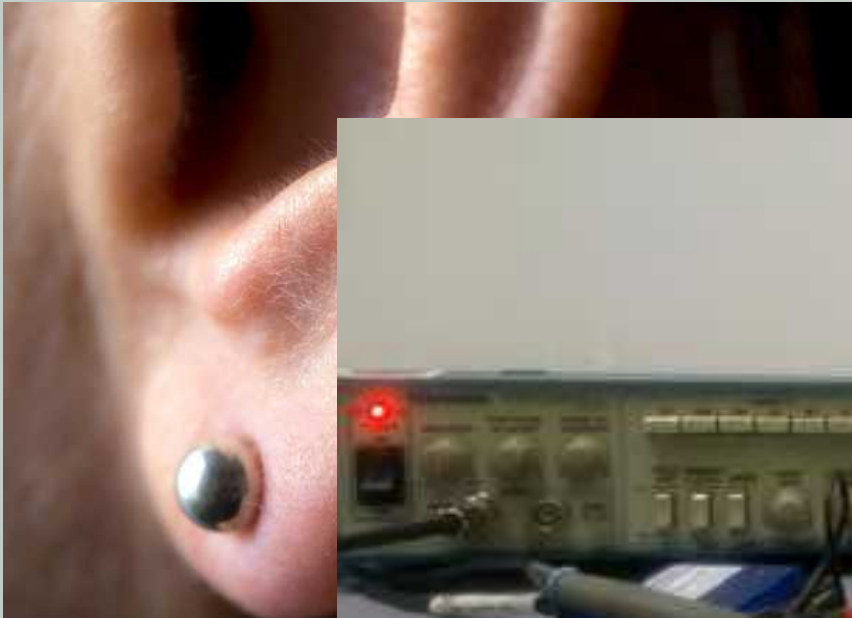


Closed
container
with water

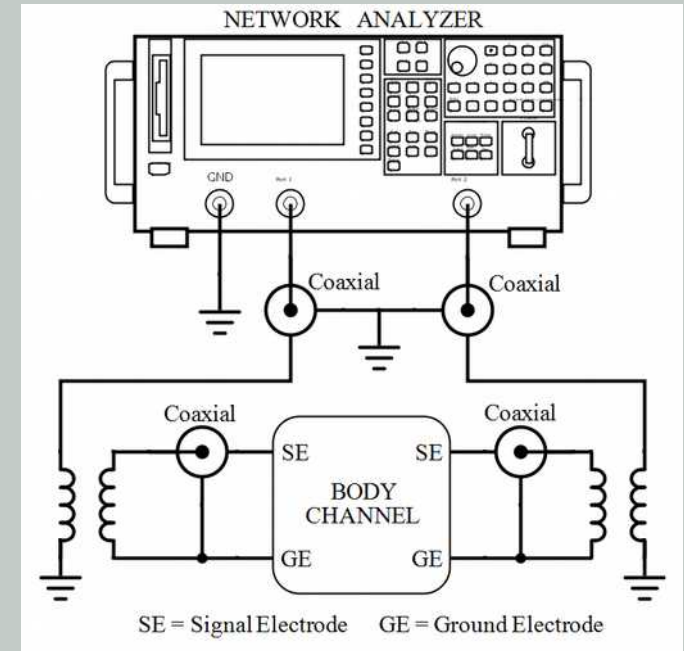
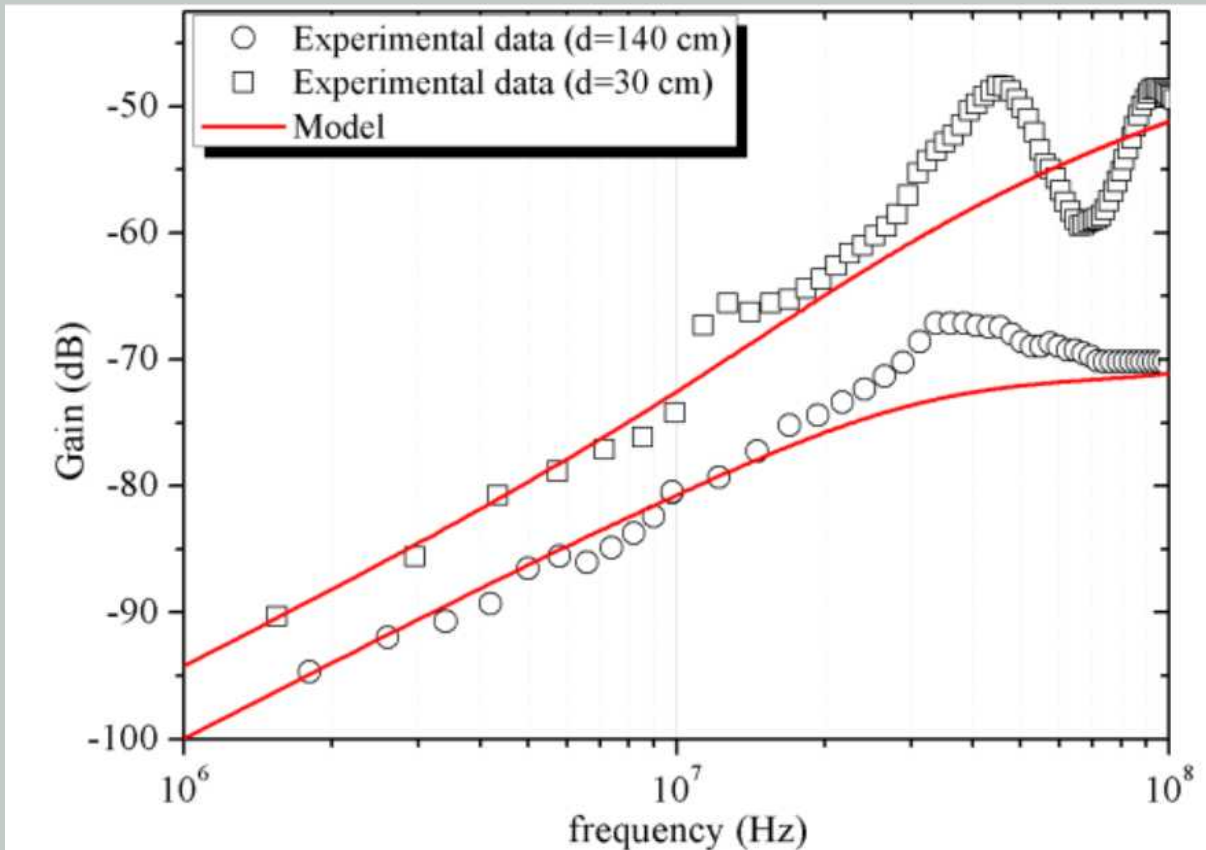


Chip para aparelhos auditivos

- Parceria com empresas



Comunicação intra-corporal



Calibration Procedure to Remove the Balun Effects on HBC Channel Measurements

G.A. Álvarez-Botero, Member, IEEE, M. D. Pereira, Member, IEEE, F. R. de Sousa, Senior Member, IEEE,

Contato

- **Contact:**

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- **More in :**

- **<http://rfic.ufsc.br>**

